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SEMICONDUCTOR

# 2N3820

## **P-Channel General Purpose Amplifier**

- This device is designed primarily for low level audio and general purpose applications with high impedance signal sources.
- Sourced from process 89.



1. Drain 2. Gate 3. Source

# **Epitaxial Silicon Transistor**

## Absolute Maximum Ratings\* T<sub>C</sub>=25°C unless otherwise noted

| Symbol           | Parameter  | Ratings   | Units |
|------------------|--|-----------|-------|
| V <sub>DG</sub>  | Drain-Gate Voltage   | -20       | V     |
| V <sub>GS</sub>  | Gate-Source Voltage  | 20        | V     |
| I <sub>GF</sub>  | Forward Gate Current   | 10        | mA    |
| T <sub>STG</sub> | Storage Temperature Range  | -55 ~ 150 | °C    |
|                  | g values above which the serviceability of any semiconductor device may be impaired. | 1         |       |

NOTES:

1) These rating are based on a maximum junction temperature of 150 degrees C.
2) These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## Electrical Characteristics $T_C=25^{\circ}C$ unless otherwise noted

| Symbol                | Parameter                         | Test Condition                          | Min. | Тур. | Max. | Units |  |  |
|-----------------------|-----------------------------------|---|------|------|------|-------|--|--|
| Off Characteristics   |                                   |   |      |      |      |       |  |  |
| V <sub>(BR)GSS</sub>  | Gate-Source Breakdwon Voltage     | $I_{G} = 10\mu A, V_{DS} = 0$           | 20   |      |      | V     |  |  |
| I <sub>GSS</sub>      | Gate Reverse Current              | $V_{GS} = 10V, V_{DS} = 0$              |      |      | 20   | nA    |  |  |
| V <sub>GS</sub> (off) | Gate-Source Cutoff Voltage        | $V_{DS} = -10V, I_{D} = -10\mu A$       |      |      | 8.0  | V     |  |  |
| On Chara              | cteristics                        |   |      |      |      |       |  |  |
| I <sub>DSS</sub>      | Zero-Gate Voltage Drain Current * | $V_{DS} = -10V, V_{GS} = 0$             | -0.3 |      | -15  | mA    |  |  |
| Small Sig             | nal Characteristics               | ·                                       |      |      |      |       |  |  |
| gfs                   | Forward Transfer Conductance      | $V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$ | 800  |      | 5000 | μmhos |  |  |
| C <sub>iss</sub>      | Input Capacitance                 | $V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$ |      |      | 32   | pF    |  |  |
| C <sub>rss</sub>      | Reverse Transfer Capacitance      | $V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$ |      |      | 16   | pF    |  |  |

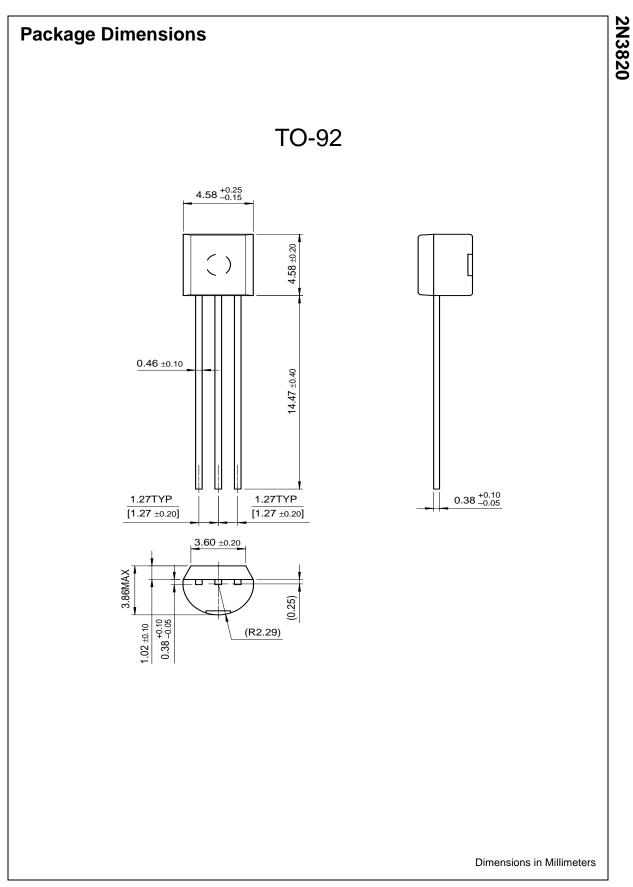
\* Pulse Test: Pulse Width  $\leq$  300ms, Duty Cycle  $\leq$  2%

### Thermal Characteristics T<sub>A</sub>=25°C unless otherwise noted

| Symbol           | Parameter                               | Max. | Units |
|------------------|---|------|-------|
| PD               | Total Device Dissipation                | 350  | mW    |
|                  | Derate above 25°C                       | 2.8  | mW/°C |
| $R_{\thetaJC}$   | Thermal Resistance, Junction to Case    | 125  | °C/W  |
| R <sub>θJA</sub> | Thermal Resistance, Junction to Ambient | 357  | °C/W  |

Device mounted on FR-4 PCB 1.6"  $\times$  1.6"  $\times$  0.06'

2N3820



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